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- Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications
- Operates at 3.3-V V<sub>CC</sub>
- LVTTL-Compatible Inputs and Outputs
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- Distributes One Clock Input to Ten Outputs
- Outputs Have Internal Series Damping Resistor to Reduce Transmission Line Effects
- Distributed V<sub>CC</sub> and Ground Pins Reduce Switching Noise
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages

	(101	VIL VV)	
GND		J <sub>24</sub>	] GND
Y10	2	23	] Y1
V <sub>CC</sub>	3	22	] v <sub>cc</sub>
Y9	4	21	] Y2
OE	5	20	] GND
Α	6	19	] Y3
P0	7	18	] Y4
P1	8	17	] GND
Y8	9	16	] Y5
V <sub>CC</sub>	10	15	] v <sub>cc</sub>
Y7	11	14	] Y6
GND	12	13	] GND

DB OR DW PACKAGE (TOP VIEW)

### description

The CDC2351 is a high-performance clock-driver circuit that distributes one input (A) to ten outputs (Y) with minimum skew for clock distribution. The output-enable  $(\overline{OE})$  input disables the outputs to a high-impedance state. Each output has an internal series damping resistor to improve signal integrity at the load. The CDC2351 operates at nominal 3.3-V  $V_{CC}$ .

The propagation delays are adjusted at the factory using the P0 and P1 pins. The factory adjustments ensure that the part-to-part skew is minimized and is kept within a specified window. Pins P0 and P1 are not intended for customer use and should be connected to GND.

The CDC2351 is characterized for operation from 0°C to 70°C.

### **FUNCTION TABLE**

INP	UTS	OUTPUTS		
Α	OE	Yn		
L	Н	Z		
Н	Н	Z		
L	L	L		
Н	L	Н		

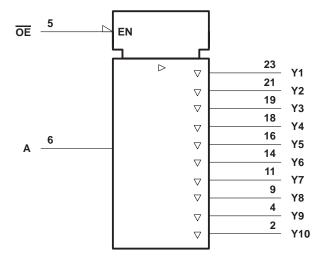


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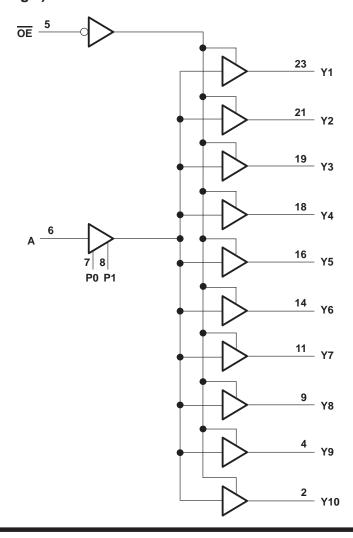


### logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### logic diagram (positive logic)





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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Voltage range applied to any output in the high state or power-off state,	
V <sub>O</sub> (see Note 1)	0.5 V to 3.6 V
Current into any output in the low state, I <sub>O</sub>	24 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	
Output clamp current, $I_{OK}(V_I < 0)$	
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DB package	0.65 W
	1.7 W
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	3	3.6	V
VIH	High-level input voltage	2		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
VI	Input voltage	0	5.5	V
IOH	High-level output current		-12	mA
loL	Low-level output current		12	mA
f <sub>clock</sub>	Input clock frequency		100	MHz
TA	Operating free-air temperature	0	70	°C

NOTE 3: Unused pins (input or I/O) must be held high or low.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITION	NS	MIN	TYP	MAX	UNIT
VIK	$V_{CC} = 3 V$ ,	$I_{ } = -18 \text{ mA}$				-1.2	V
Voн	$V_{CC} = 3 V$ ,	$I_{OH} = -12 \text{ mA}$		2			V
V <sub>OL</sub>	V <sub>CC</sub> = 3 V,	$I_{OL}$ = 12 mA				0.8	V
lį	V <sub>CC</sub> = 3.6 V,	$V_I = V_{CC}$ or GND				±1	μΑ
10 <sup>‡</sup>	V <sub>CC</sub> = 3.6 V,	V <sub>O</sub> = 2.5 V	V <sub>O</sub> = 2.5 V			-70	mA
loz	V <sub>CC</sub> = 3.6 V,	$V_{CC} = 3 \text{ V or } 0$				±10	μΑ
	.,		Outputs high			0.3	
lcc	$V_{CC} = 3.6 \text{ V},$ $V_{I} = V_{CC} \text{ or GND}$	$I_{O}=0,$	Outputs low			15	mA
	VI = VCC OI GIVD	Outputs disabled			0.3		
Ci	$V_I = V_{CC}$ or GND,	$V_{CC} = 3.3 \text{ V},$	f = 10 MHz		4		pF
Co	$V_O = V_{CC}$ or GND,	V <sub>CC</sub> = 3.3 V,	f = 10 MHz		6		pF

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

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### switching characteristics, C<sub>L</sub> = 50 pF (see Figures 1 and 2)

PARAMETER	FROM	TO (OUTPUT)	V <sub>CC</sub> = 3.3 V, T <sub>A</sub> = 25°C			V <sub>CC</sub> = 3 V to 3.6 V, T <sub>A</sub> = 0°C to 70°C		UNIT
	(INPUT)		MIN	TYP	MAX	MIN	MAX	
<sup>t</sup> PLH	А	Y	3.8	4.3	4.8			ns
<sup>t</sup> PHL	A	· [	3.6	4.1	4.6			119
<sup>t</sup> PZH	ŌĒ	Υ	2.4	4.9	6.0	1.8	6.9	ne
t <sub>PZL</sub>		'	2.4	4.3	6.0	1.8	6.9	ns
<sup>t</sup> PHZ	ŌĒ	Υ	2.2	4.4	6.3	2.1	7.1	ns
t <sub>PLZ</sub>		ı	2.2	4.6	6.3	2.1	7.3	115
<sup>t</sup> sk(o)	Α	Υ		0.3	0.5		0.5	ns
<sup>t</sup> sk(p)	А	Υ		0.2	0.8		0.8	ns
<sup>t</sup> sk(pr)	А	Υ			1		1	ns
t <sub>r</sub>	А	Υ					2.5	ns
t <sub>f</sub>	А	Υ				·	2.5	ns

# switching characteristics temperature and $V_{\hbox{CC}}$ coefficients over recommended operating free-air temperature and $V_{\hbox{CC}}$ range (see Note 4)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	MIN MAX	UNIT
∝t <sub>PLH</sub> (T)	Average temperature coefficient of low to high propagation delay	А	Y	85†	ps/10°C
∝t <sub>PHL</sub> (T)	Average temperature coefficient of high to low propagation delay	А	Υ	50†	ps/10°C
∝tPLH(VCC)	Average V <sub>CC</sub> coefficient of low to high propagation delay	А	Υ	-145 <sup>‡</sup>	ps/ 100 mV
∝t <sub>PHL</sub> (V <sub>CC</sub> )	Average V <sub>CC</sub> coefficient of high to low propagation delay	А	Y	-100‡	ps/ 100 mV

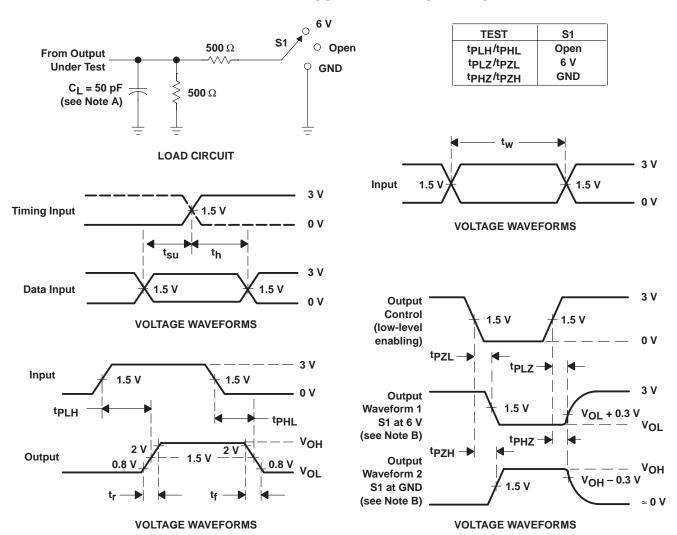
†  $\propto$ tpLH(T) and  $\propto$ tpHL(T) are virtually independent of V<sub>CC</sub>.

‡  $\propto$ tpLH(V<sub>CC</sub>) and  $\propto$ tpHL(V<sub>CC</sub>) are virtually independent of temperature.

NOTE 4: These data were extracted from characterization material and are not tested at the factory.



### PARAMETER MEASUREMENT INFORMATION

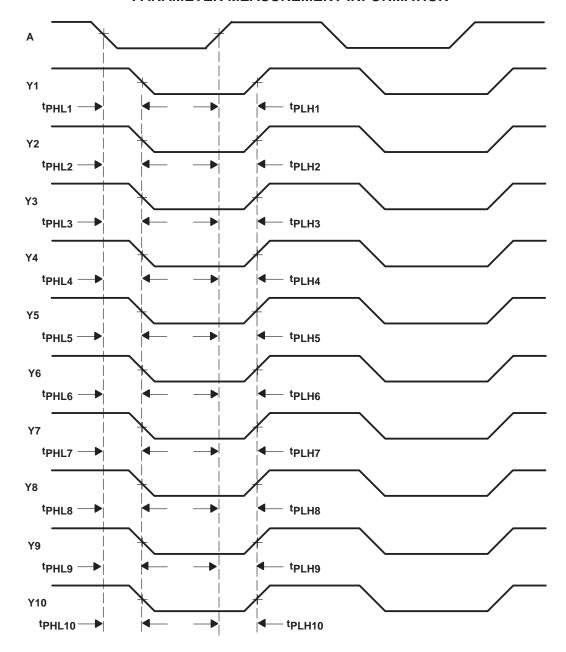


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Output skew,  $t_{sk(0)}$ , is calculated as the greater of:

   The difference between the fastest and slowest of  $t_{PLHn}$  (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10)
  - The difference between the fastest and slowest of tpHLn (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10)
  - B. Pulse skew,  $t_{sk(p)}$ , is calculated as the greater of  $|t_{PLHn} t_{PHLn}|$  (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10).

  - C. Process skew, t<sub>Sk(pr)</sub>, is calculated as the greater of:

     The difference between the fastest and slowest of t<sub>PLHn</sub> (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10) across multiple devices under identical operating conditions
    - The difference between the fastest and slowest of  $t_{PHLn}$  (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10) across multiple devices under identical operating conditions

Figure 2. Waveforms for Calculation of  $t_{sk(o)}$ ,  $t_{sk(p)}$ ,  $t_{sk(pr)}$ 



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